

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. **(Original)** Method for producing fully ceramic tooth elements having a pre-determined spatial form by means of electrophoresis, characterized in that an electrically conductive chip or chip which has been rendered electrically conductive is arranged directly on a working model or on a part of the framework, whereby the chip can comprise regions of different electrical conductivity and is connected preferably to the positive pole during the electrophoresis.
2. **(Original)** Method according to Claim 1, characterized in that the framework material is being deposited.
3. **(Original)** Method according to Claim 1, characterized in that the veneering material is being deposited.
4. **(Currently Amended)** Method according to ~~any one of the Claims 1 to 3~~ Claim 1, characterized in that the chip is a synthetic paper made electrically conductive by means of a salt solution.
5. **(Currently Amended)** Method according to ~~any one of the Claims 1 to 4~~ Claim 1, characterized in that the areas of lower electrical resistance are generated by means of aluminum foil.
6. **(Original)** Method according to Claim 2, characterized in that an alumina or zirconia slip is used.
7. **(Original)** Method according to Claim 4, characterized in that nylon is used as the chip material.
8. **(Currently Amended)** Method according to Claim 1 [[or 2]], characterized in that the chip comprises alumina fibers, in particular whiskers.

9. **(Currently Amended)** Method according to Claim 1 [[to 8]], characterized in that an electrically conductive foil, e.g. made of aluminum, is arranged between two fibrous layers of the chip.
10. **(Currently Amended)** Method according to ~~any one of the Claims 1 to 9~~ Claim 1, characterized in that the chip is made electrically conductive by means of saline solution.
11. **(Currently Amended)** Method according to ~~any one of the Claims 1 to 10~~ Claim 1, characterized in that the chip has a T-shaped cross-section.
12. **(Currently Amended)** Method according to ~~any one of the Claims 1 to 8~~ Claim 1, characterized in that the chip is wider in the middle than in the area of the dies.